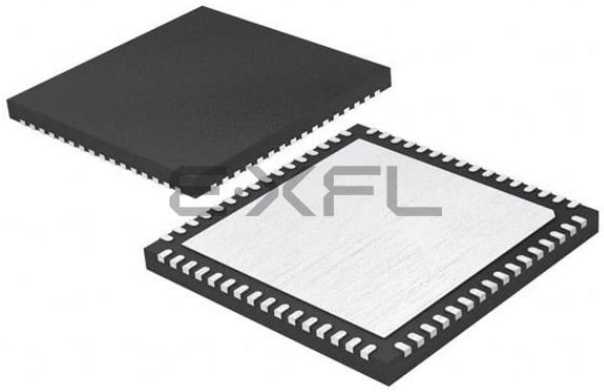

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, Motor Control PWM, POR, PWM, WDT
Number of I/O	53
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	48K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 30x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep512gm306-e-mr

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Type	Buffer Type	PPS	Description
U1CTS	I	ST	Yes	UART1 Clear-to-Send.
U1RTS	O	—	Yes	UART1 Ready-to-Send.
U1RX	I	ST	Yes	UART1 receive.
U1TX	O	—	Yes	UART1 transmit.
U2CTS	I	ST	Yes	UART2 Clear-to-Send.
U2RTS	O	—	Yes	UART2 Ready-to-Send.
U2RX	I	ST	Yes	UART2 receive.
U2TX	O	—	Yes	UART2 transmit.
U3CTS	I	ST	Yes	UART3 Clear-to-Send.
U3RTS	O	—	Yes	UART3 Ready-to-Send.
U3RX	I	ST	Yes	UART3 receive.
U3TX	O	—	Yes	UART3 transmit.
U4CTS	I	ST	Yes	UART4 Clear-to-Send.
U4RTS	O	—	Yes	UART4 Ready-to-Send.
U4RX	I	ST	Yes	UART4 receive.
U4TX	O	—	Yes	UART4 transmit.
SCK1	I/O	ST	No	Synchronous serial clock input/output for SPI1.
SDI1	I	ST	No	SPI1 data in.
SDO1	O	—	No	SPI1 data out.
SS1	I/O	ST	No	SPI1 slave synchronization or frame pulse I/O.
SCK2	I/O	ST	Yes	Synchronous serial clock input/output for SPI2.
SDI2	I	ST	Yes	SPI2 data in.
SDO2	O	—	Yes	SPI2 data out.
SS2	I/O	ST	Yes	SPI2 slave synchronization or frame pulse I/O.
SCK3	I/O	ST	Yes	Synchronous serial clock input/output for SPI3.
SDI3	I	ST	Yes	SPI3 data in.
SDO3	O	—	Yes	SPI3 data out.
SS3	I/O	ST	Yes	SPI3 slave synchronization or frame pulse I/O.
SCL1	I/O	ST	No	Synchronous serial clock input/output for I2C1.
SDA1	I/O	ST	No	Synchronous serial data input/output for I2C1.
ASCL1	I/O	ST	No	Alternate synchronous serial clock input/output for I2C1.
ASDA1	I/O	ST	No	Alternate synchronous serial data input/output for I2C1.
SCL2	I/O	ST	No	Synchronous serial clock input/output for I2C2.
SDA2	I/O	ST	No	Synchronous serial data input/output for I2C2.
ASCL2	I/O	ST	No	Alternate synchronous serial clock input/output for I2C2.
ASDA2	I/O	ST	No	Alternate synchronous serial data input/output for I2C2.
TMS	I	ST	No	JTAG Test mode select pin.
TCK	I	ST	No	JTAG test clock input pin.
TDI	I	ST	No	JTAG test data input pin.
TDO	O	—	No	JTAG test data output pin.

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
PPS = Peripheral Pin Select; TTL = TTL input buffer

Note 1: This pin is not available on all devices. For more information, see the **"Pin Diagrams"** section for pin availability.

2: AVDD must be connected at all times.

FIGURE 2-7: INTERLEAVED PFC

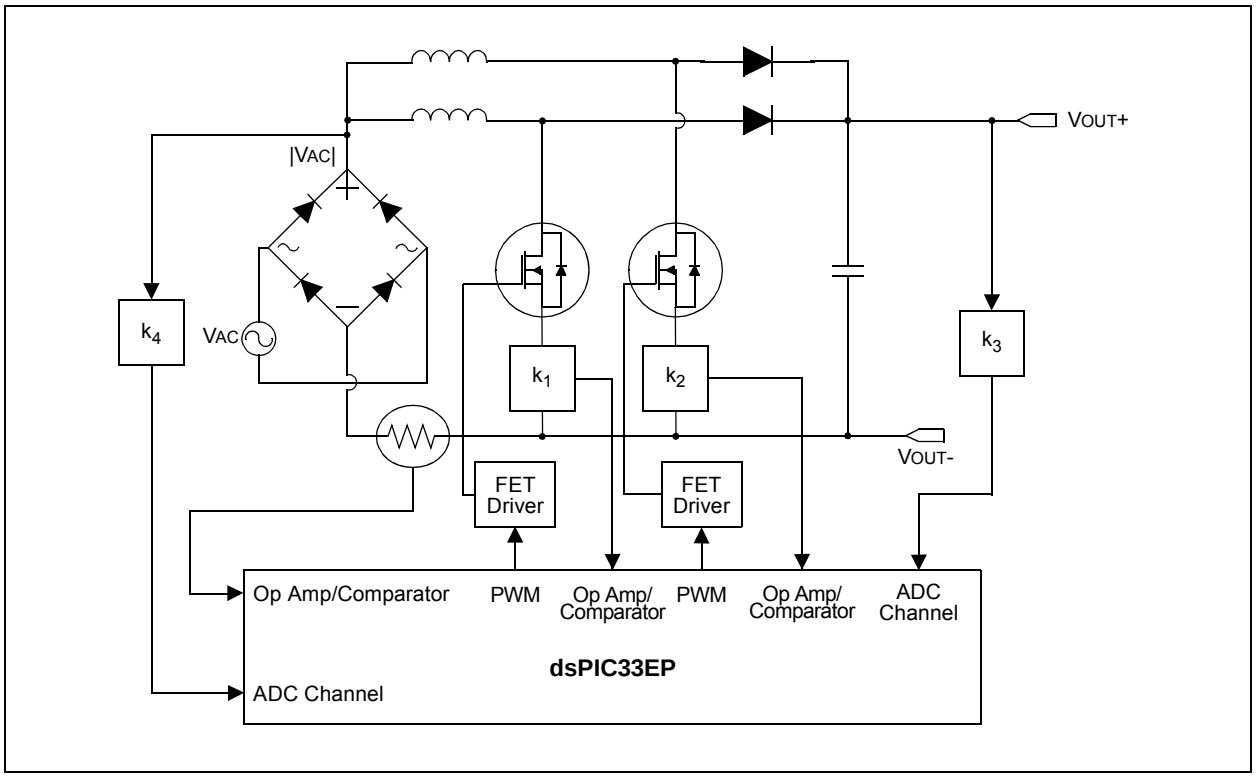
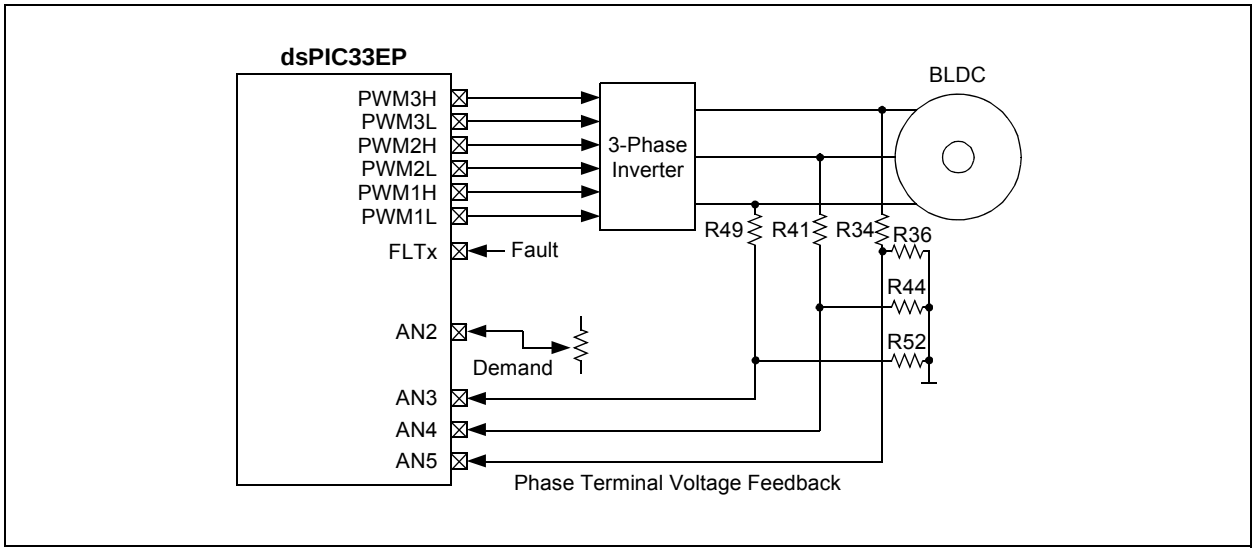


FIGURE 2-8: BEMF VOLTAGE MEASURED USING THE ADC MODULE



4.1.1 PROGRAM MEMORY ORGANIZATION

The program memory space is organized in word-addressable blocks. Although it is treated as 24 bits wide, it is more appropriate to think of each address of the program memory as a lower and upper word, with the upper byte of the upper word being unimplemented. The lower word always has an even address, while the upper word has an odd address (Figure 4-4).

Program memory addresses are always word-aligned on the lower word and addresses are incremented or decremented by two during code execution. This arrangement provides compatibility with data memory space addressing and makes data in the program memory space accessible.

4.1.2 INTERRUPT AND TRAP VECTORS

All dsPIC33EPXXXGM3XX/6XX/7XX devices reserve the addresses between 0x000000 and 0x000200 for hard-coded program execution vectors. A hardware Reset vector is provided to redirect code execution from the default value of the PC on device Reset to the actual start of code. A GOTO instruction is programmed by the user application at address, 0x000000 of Flash memory, with the actual address for the start of code at address, 0x000002 of Flash memory.

A more detailed discussion of the interrupt vector tables is provided in **Section 7.1 "Interrupt Vector Table"**.

FIGURE 4-4: PROGRAM MEMORY ORGANIZATION

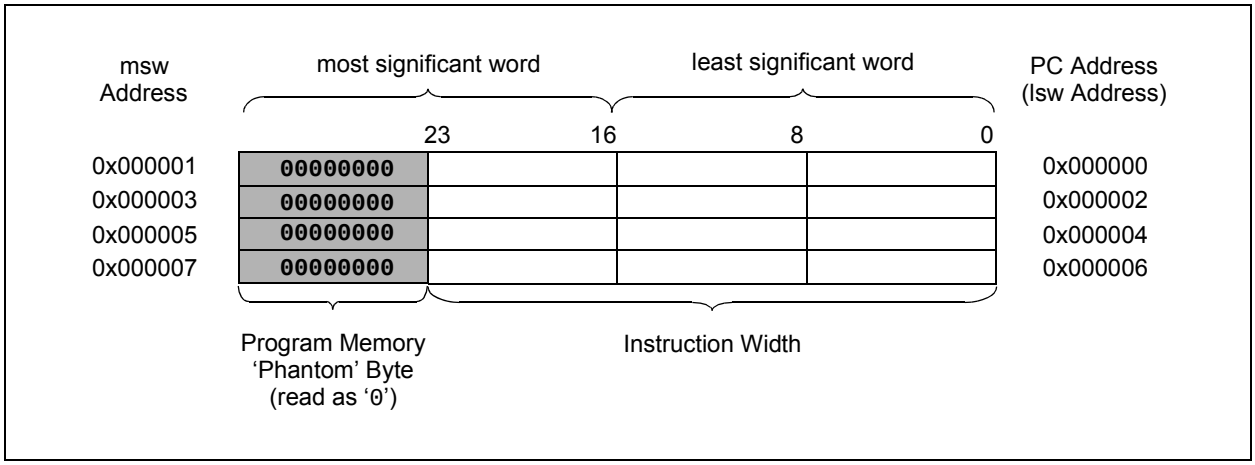


TABLE 4-41: OP AMP/COMPARATOR REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
CMSTAT	0A80	PSIDL	—	—	C5EVT	C4EVT	C3EVT	C2EVT	C1EVT	—	—	—	C5OUT	C4OUT	C3OUT	C2OUT	C1OUT	0000
CVR1CON	0A82	—	—	—	—	CVRR1	VREFSEL	—	—	CVREN	CVROE	CVRR0	CVRSS	CVR3	CVR2	CVR1	CVR0	0000
CM1CON	0A84	CON	COE	CPOL	—	—	OPMODE	CEVT	COUT	EVPOL1	EVPOL0	—	CREF	—	—	CCH1	CCH0	0000
CM1MSKSRC	0A86	—	—	—	—	SELSRCC3	SELSRCC2	SELSRCC1	SELSRCC0	SELSRCB3	SELSRCB2	SELSRCB1	SELSRCB0	SELSRCA3	SELSRCA2	SELSRCA1	SELSRCA0	0000
CM1MSKCON	0A88	HLMS	—	OCEN	OCNEN	OBEN	OBNEN	OAEN	OANEN	NAGS	PAGS	ACEN	ACNEN	ABEN	ABNEN	AAEN	AANEN	0000
CM1FLTR	0A8A	—	—	—	—	—	—	—	—	—	CFSEL2	CFSEL1	CFSEL0	CFLTREN	CFDIV2	CFDIV1	CFDIV0	0000
CM2CON	0A8C	CON	COE	CPOL	—	—	OPMODE	CEVT	COUT	EVPOL1	EVPOL0	—	CREF	—	—	CCH1	CCH0	0000
CM2MSKSRC	0A8E	—	—	—	—	SELSRCC3	SELSRCC2	SELSRCC1	SELSRCC0	SELSRCB3	SELSRCB2	SELSRCB1	SELSRCB0	SELSRCA3	SELSRCA2	SELSRCA1	SELSRCA0	0000
CM2MSKCON	0A90	HLMS	—	OCEN	OCNEN	OBEN	OBNEN	OAEN	OANEN	NAGS	PAGS	ACEN	ACNEN	ABEN	ABNEN	AAEN	AANEN	0000
CM2FLTR	0A92	—	—	—	—	—	—	—	—	—	CFSEL2	CFSEL1	CFSEL0	CFLTREN	CFDIV2	CFDIV1	CFDIV0	0000
CM3CON	0A94	CON	COE	CPOL	—	—	OPMODE	CEVT	COUT	EVPOL1	EVPOL0	—	CREF	—	—	CCH1	CCH0	0000
CM3MSKSRC	0A96	—	—	—	—	SELSRCC3	SELSRCC2	SELSRCC1	SELSRCC0	SELSRCB3	SELSRCB2	SELSRCB1	SELSRCB0	SELSRCA3	SELSRCA2	SELSRCA1	SELSRCA0	0000
CM3MSKCON	0A98	HLMS	—	OCEN	OCNEN	OBEN	OBNEN	OAEN	OANEN	NAGS	PAGS	ACEN	ACNEN	ABEN	ABNEN	AAEN	AANEN	0000
CM3FLTR	0A9A	—	—	—	—	—	—	—	—	—	CFSEL2	CFSEL1	CFSEL0	CFLTREN	CFDIV2	CFDIV1	CFDIV0	0000
CM4CON	0A9C	CON	COE	CPOL	—	—	—	CEVT	COUT	EVPOL1	EVPOL0	—	CREF	—	—	CCH1	CCH0	0000
CM4MSKSRC	0A9E	—	—	—	—	SELSRCC3	SELSRCC2	SELSRCC1	SELSRCC0	SELSRCB3	SELSRCB2	SELSRCB1	SELSRCB0	SELSRCA3	SELSRCA2	SELSRCA1	SELSRCA0	0000
CM4MSKCON	0AA0	HLMS	—	OCEN	OCNEN	OBEN	OBNEN	OAEN	OANEN	NAGS	PAGS	ACEN	ACNEN	ABEN	ABNEN	AAEN	AANEN	0000
CM4FLTR	0AA2	—	—	—	—	—	—	—	—	—	CFSEL2	CFSEL1	CFSEL0	CFLTREN	CFDIV2	CFDIV1	CFDIV0	0000
CM5CON	0AA4	CON	COE	CPOL	—	—	OPMODE	CEVT	COUT	EVPOL1	EVPOL0	—	CREF	—	—	CCH1	CCH0	0000
CM5MSKSRC	0AA6	—	—	—	—	SELSRCC3	SELSRCC2	SELSRCC1	SELSRCC0	SELSRCB3	SELSRCB2	SELSRCB1	SELSRCB0	SELSRCA3	SELSRCA2	SELSRCA1	SELSRCA0	0000
CM5MSKCON	0AA8	HLMS	—	OCEN	OCNEN	OBEN	OBNEN	OAEN	OANEN	NAGS	PAGS	ACEN	ACNEN	ABEN	ABNEN	AAEN	AANEN	0000
CM5FLTR	0AAA	—	—	—	—	—	—	—	—	—	CFSEL2	CFSEL1	CFSEL0	CFLTREN	CFDIV2	CFDIV1	CFDIV0	0000
CVR2CON	0AB4	—	—	—	—	CVRR1	VREFSEL	—	—	CVREN	CVROE	CVRR0	CVRSS	CVR3	CVR2	CVR1	CVR0	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 11-1: SELECTABLE INPUT SOURCES (MAPS INPUT TO FUNCTION) (CONTINUED)

Input Name(1)	Function Name	Register	Configuration Bits
PWM Sync Input 1	SYNCI1	RPINR37	SYNCI1R<6:0>
PWM Dead-Time Compensation 1	DTCMP1	RPINR38	DTCMP1R<6:0>
PWM Dead-Time Compensation 2	DTCMP2	RPINR39	DTCMP2R<6:0>
PWM Dead-Time Compensation 3	DTCMP3	RPINR39	DTCMP3R<6:0>
PWM Dead-Time Compensation 4	DTCMP4	RPINR40	DTCMP4R<6:0>
PWM Dead-Time Compensation 5	DTCMP5	RPINR40	DTCMP5R<6:0>
PWM Dead-Time Compensation 6	DTCMP6	RPINR41	DTCMP6R<6:0>

Note 1: Unless otherwise noted, all inputs use the Schmitt Trigger input buffers.

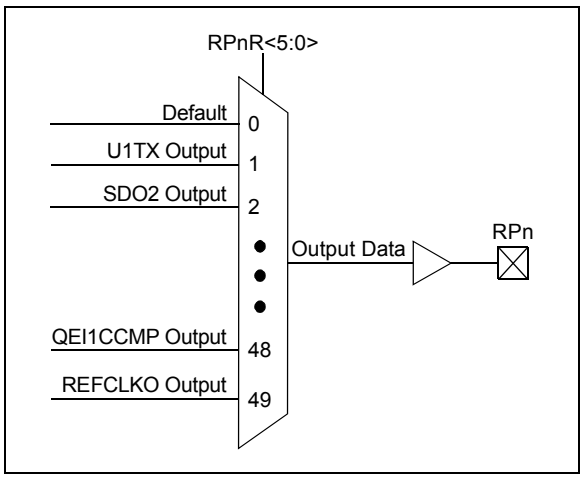
2: This input is available on dsPIC33EPXXXGM6XX/7XX devices only.

11.4.5 OUTPUT MAPPING

In contrast to inputs, the outputs of the Peripheral Pin Select options are mapped on the basis of the pin. In this case, a control register associated with a particular pin dictates the peripheral output to be mapped. The RPORx registers are used to control output mapping. Like the RPINRx registers, each register contains sets of 6-bit fields, with each set associated with one RPn pin (see Register 11-30 through Register 11-42). The value of the bit field corresponds to one of the peripherals and that peripheral's output is mapped to the pin (see Table 11-3 and Figure 11-3).

A null output is associated with the output register Reset value of '0'. This is done to ensure that remappable outputs remain disconnected from all output pins by default.

FIGURE 11-3: MULTIPLEXING REMAPPABLE OUTPUT FOR RPn



11.4.5.1 Mapping Limitations

The control schema of the peripheral select pins is not limited to a small range of fixed peripheral configurations. There are no mutual or hardware-enforced lockouts between any of the peripheral mapping SFRs. Literally any combination of peripheral mappings across any or all of the RPn pins is possible. This includes both many-to-one and one-to-many mappings of peripheral inputs and outputs to pins. While such mappings may be technically possible from a configuration point of view, they may not be supportable from an electrical point of view.

REGISTER 11-20: RPINR26: PERIPHERAL PIN SELECT INPUT REGISTER 26(1)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	C2RXR<6:0>						
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	C1RXR<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-8 **C2RXR<6:0>:** Assign CAN2 RX Input (C2RX) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111100 = Input tied to RPI124
•
•
•
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

bit 7 **Unimplemented:** Read as ‘0’

bit 6-0 **C1RXR<6:0>:** Assign CAN1 RX Input (C1RX) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111100 = Input tied to RPI124
•
•
•
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

Note 1: This register is not available on dsPIC33EPXXXGM3XX devices.

15.0 OUTPUT COMPARE

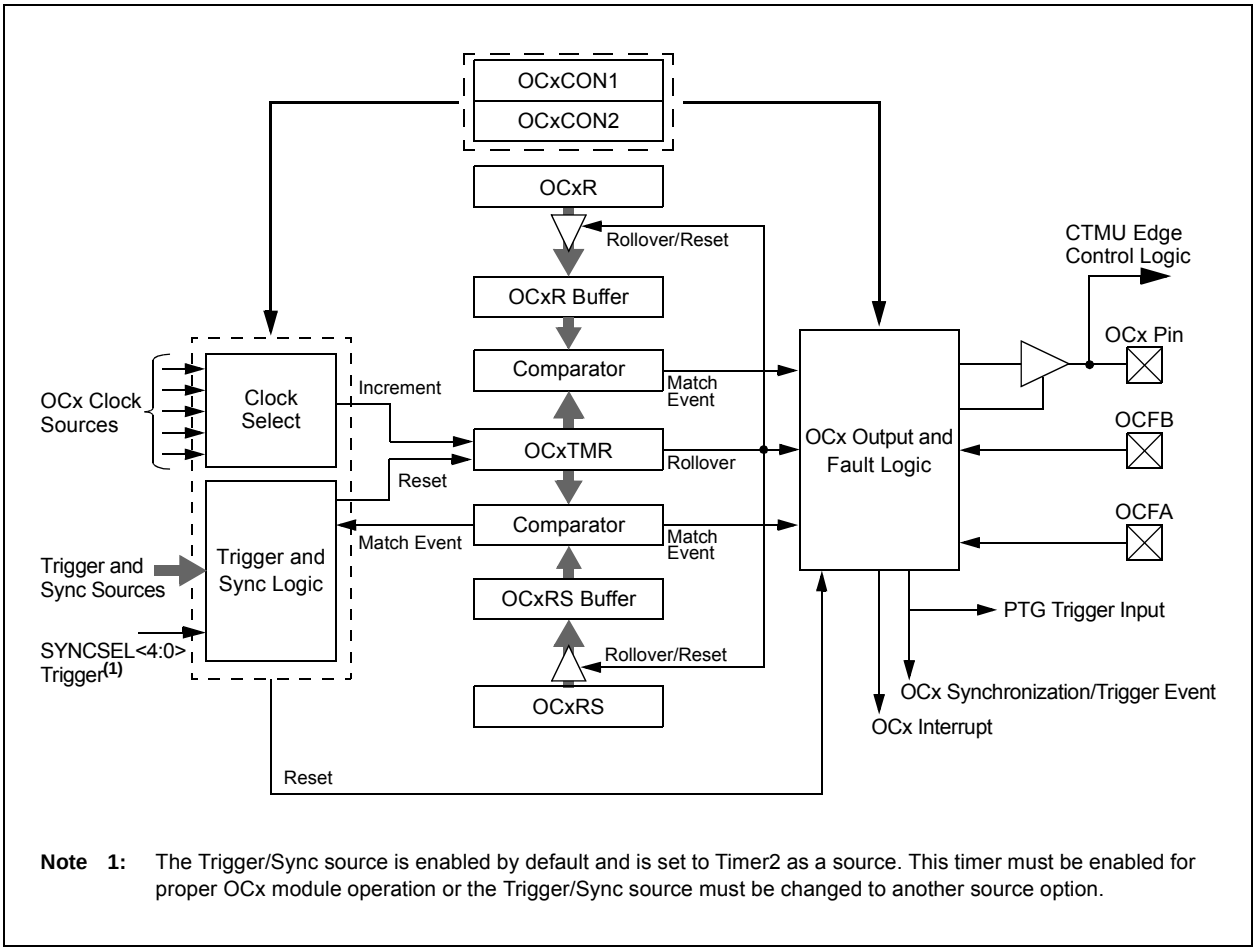
Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGM3XX/6XX/7XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the *"dsPIC33/PIC24EFamily Reference Manual"*, **"Output Compare"** (DS70005157), which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The output compare module can select one of eight available clock sources for its time base. The module compares the value of the timer with the value of one or two Compare registers depending on the operating mode selected. The state of the output pin changes when the timer value matches the Compare register value. The output compare module generates either a single output pulse, or a sequence of output pulses, by changing the state of the output pin on the compare match events. The output compare module can also generate interrupts on compare match events and trigger DMA data transfers.

Note: See the *"dsPIC33/PIC24 Family Reference Manual"*, **"Output Compare"** (DS70005157) for OCxR and OCxRS register restrictions.

FIGURE 15-1: OUTPUT COMPARE x MODULE BLOCK DIAGRAM



Note 1: The Trigger/Sync source is enabled by default and is set to Timer2 as a source. This timer must be enabled for proper OCx module operation or the Trigger/Sync source must be changed to another source option.

REGISTER 16-25: PWMCAPx: PWMx PRIMARY TIME BASE CAPTURE REGISTER

R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
PWMCAPx<15:8>(1,2)							
bit 15							bit 8

R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
PWMCAPx<7:0>(1,2)							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **PWMCAPx<15:0>:** PWMx Captured Time Base Value bits(1,2)
The value in this register represents the captured PWMx time base value when a leading edge is detected on the current-limit input.

Note 1: The capture feature is only available on a primary output (PWMxH).
2: This feature is active only after LEB processing on the current-limit input signal is complete.

20.1 UART Helpful Tips

1. In multi-node direct connect UART networks, UART receive inputs react to the complementary logic level defined by the URXINV bit (UxMODE<4>), which defines the Idle state, the default of which is logic high (i.e., URXINV = 0). Because remote devices do not initialize at the same time, it is likely that one of the devices, because the RX line is floating, will trigger a Start bit detection and will cause the first byte received, after the device has been initialized, to be invalid. To avoid this situation, the user should use a pull-up or pull-down resistor on the RX pin, depending on the value of the URXINV bit.
   a) If URXINV = 0, use a pull-up resistor on the RX pin.
   b) If URXINV = 1, use a pull-down resistor on the RX pin.
2. The first character received on wake-up from Sleep mode, caused by activity on the UxRX pin of the UART module, will be invalid. In Sleep mode, peripheral clocks are disabled. By the time the oscillator system has restarted and stabilized from Sleep mode, the baud rate bit sampling clock, relative to the incoming UxRX bit timing, is no longer synchronized, resulting in the first character being invalid. This is to be expected.

25.0 PERIPHERAL TRIGGER GENERATOR (PTG) MODULE

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGM3XX/6XX/7XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"Peripheral Trigger Generator (PTG)"** (DS70669), which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

25.1 Module Introduction

The Peripheral Trigger Generator (PTG) provides a means to schedule complex, high-speed peripheral operations that would be difficult to achieve using software. The PTG module uses 8-bit commands, called "steps", that the user writes to the PTG Queue register (PTGQUE0-PTQUE15), which performs operations, such as wait for input signal, generate output trigger and wait for timer.

The PTG module has the following major features:

- Multiple Clock Sources
- Two 16-Bit General Purpose Timers
- Two 16-Bit General Limit Counters
- Configurable for Rising or Falling Edge Triggering
- Generates Processor Interrupts to Include:
  - Four configurable processor interrupts
  - Interrupt on a step event in Single-Step mode
  - Interrupt on a PTG Watchdog Timer time-out
- Able to Receive Trigger Signals from these Peripherals:
  - ADC
  - PWM
  - Output Compare
  - Input Capture
  - Op Amp/Comparator
  - INT2
- Able to Trigger or Synchronize to these Peripherals:
  - Watchdog Timer
  - Output Compare
  - Input Capture
  - ADC
  - PWM
  - Op Amp/Comparator

REGISTER 26-3: CM4CON: OP AMP/COMPARATOR 4 CONTROL REGISTER

R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0
CON	COE	CPOL	—	—	—	CEVT(2)	COUT
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0
EVPOL1(2)	EVPOL0(2)	—	CREF(1)	—	—	CCH1(1)	CCH0(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CON:** Op Amp/Comparator Enable bit
1 = Comparator is enabled
0 = Comparator is disabled

bit 14 **COE:** Comparator Output Enable bit
1 = Comparator output is present on the CxOUT pin
0 = Comparator output is internal only

bit 13 **CPOL:** Comparator Output Polarity Select bit
1 = Comparator output is inverted
0 = Comparator output is not inverted

bit 12-10 **Unimplemented:** Read as '0'

bit 9 **CEVT:** Comparator Event bit(2)
1 = Comparator event, according to the EVPOL<1:0> settings, occurred; disables future triggers and interrupts until the bit is cleared
0 = Comparator event did not occur

bit 8 **COUT:** Comparator Output bit
When CPOL = 0 (non-inverted polarity):
1 = VIN+ > VIN-
0 = VIN+ < VIN-
When CPOL = 1 (inverted polarity):
1 = VIN+ < VIN-
0 = VIN+ > VIN-

Note 1: Inputs that are selected and not available will be tied to VSS. See the **"Pin Diagrams"** section for available inputs for each package.

2: After configuring the comparator, either for a high-to-low or low-to-high COUT transition (EVPOL<1:0> (CMxCON<7:6>) = 10 or 01), the Comparator Event bit, CEVT (CMxCON<9>), and the Comparator Combined Interrupt Flag, CMPIF (IFS1<2>), **must be cleared** before enabling the Comparator Interrupt Enable bit, CMPIE (IEC1<2>).

32.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers (MCU) and dsPIC® digital signal controllers (DSC) are supported with a full range of software and hardware development tools:

- Integrated Development Environment
  - MPLAB® X IDE Software
- Compilers/Assemblers/Linkers
  - MPLAB XC Compiler
  - MPASM™ Assembler
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
  - MPLAB Assembler/Linker/Librarian for Various Device Families
- Simulators
  - MPLAB X SIM Software Simulator
- Emulators
  - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers/Programmers
  - MPLAB ICD 3
  - PICkit™ 3
- Device Programmers
  - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits and Starter Kits
- Third-party development tools

32.1 MPLAB X Integrated Development Environment Software

The MPLAB X IDE is a single, unified graphical user interface for Microchip and third-party software, and hardware development tool that runs on Windows®, Linux and Mac OS® X. Based on the NetBeans IDE, MPLAB X IDE is an entirely new IDE with a host of free software components and plug-ins for high-performance application development and debugging. Moving between tools and upgrading from software simulators to hardware debugging and programming tools is simple with the seamless user interface.

With complete project management, visual call graphs, a configurable watch window and a feature-rich editor that includes code completion and context menus, MPLAB X IDE is flexible and friendly enough for new users. With the ability to support multiple tools on multiple projects with simultaneous debugging, MPLAB X IDE is also suitable for the needs of experienced users.

Feature-Rich Editor:

- Color syntax highlighting
- Smart code completion makes suggestions and provides hints as you type
- Automatic code formatting based on user-defined rules
- Live parsing

User-Friendly, Customizable Interface:

- Fully customizable interface: toolbars, toolbar buttons, windows, window placement, etc.
- Call graph window

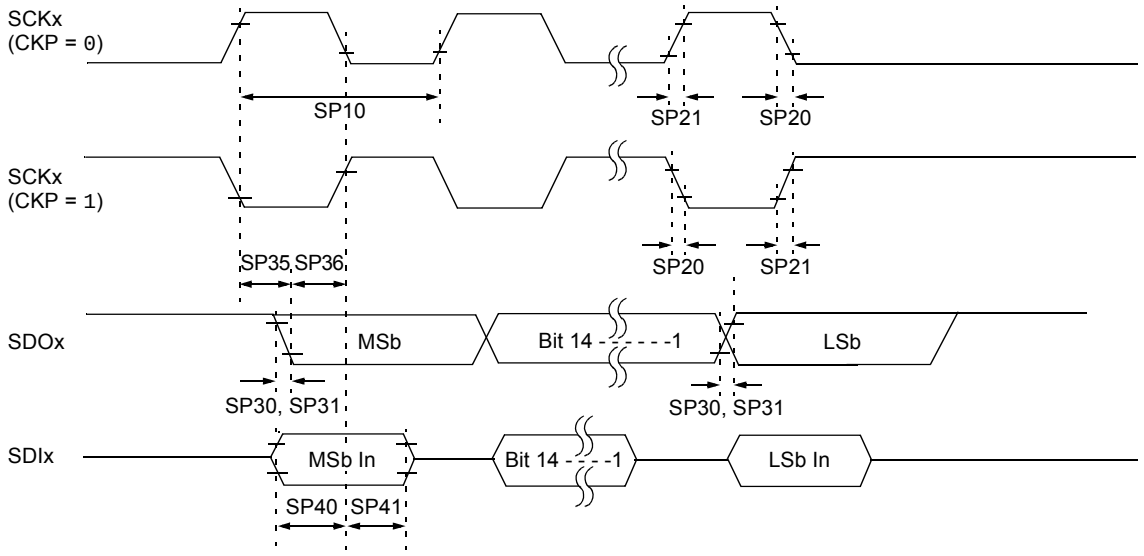
Project-Based Workspaces:

- Multiple projects
- Multiple tools
- Multiple configurations
- Simultaneous debugging sessions

File History and Bug Tracking:

- Local file history feature
- Built-in support for Bugzilla issue tracker

FIGURE 33-18: SPI2 AND SPI3 MASTER MODE (FULL-DUPLEX, CKE = 0, CKP = x, SMP = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 33-1 for load conditions.

TABLE 33-35: SPI2 AND SPI3 MASTER MODE (FULL-DUPLEX, CKE = 0, CKP = x, SMP = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	FscP	Maximum SCKx Frequency	—	—	9	MHz	-40ºC to +125ºC **(Note 3)**
SP20	TscF	SCKx Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP21	TscR	SCKx Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 111 ns. The clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

TABLE 33-44: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK1 Input Frequency	—	—	25	MHz	**(Note 3)**
SP72	TscF	SCK1 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK1 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	20	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCK1 Edge	20	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	15	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS1}$ ↓ to SCK1 ↑ or SCK1 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS1}$ ↑ to SDO1 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH TscL2ssH	$\overline{SS1}$ ↑ after SCK1 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**
SP60	TssL2doV	$\overline{SDO1}$ Data Output Valid after $\overline{SS1}$ Edge	—	—	50	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 66.7 ns. Therefore, the SCK1 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

TABLE 33-52: OP AMP/COMPARATOR SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions (see Note 3): 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
Comparator AC Characteristics							
CM10	TRESP	Response Time	—	19	—	ns	V+ input step of 100 mV, V- input held at VDD/2
CM11	TMC2OV	Comparator Mode Change to Output Valid	—	—	10	µs	
Comparator DC Characteristics							
CM30	VOFFSET	Comparator Offset Voltage	—	±20	±75	mV	
CM31	VHYST	Input Hysteresis Voltage	—	30	—	mV	
CM32	TRISE/ TFALL	Comparator Output Rise/Fall Time	—	20	—	ns	1 pF load capacitance on input
CM33	VGAIN	Open-Loop Voltage Gain	—	90	—	db	
CM34	VICM	Input Common-Mode Voltage	AVSS	—	AVDD	V	
Op Amp AC Characteristics							
CM20	SR	Slew Rate	—	9	—	V/µs	10 pF load
CM21a	PM	Phase Margin	—	68	—	Degree	G = 100V/V; 10 pF load
CM22	GM	Gain Margin	—	20	—	db	G = 100V/V; 10 pF load
CM23a	GBW	Gain Bandwidth	—	10	—	MHz	10 pF load
Op Amp DC Characteristics							
CM40	VCMR	Common-Mode Input Voltage Range	AVSS	—	AVDD	V	
CM41	CMRR	Common-Mode Rejection Ratio	—	40	—	db	VCM = AVDD/2
CM42	VOFFSET	Op Amp Offset Voltage	—	±20	±70	mV	
CM43	VGAIN	Open-Loop Voltage Gain	—	90	—	db	
CM44	IOS	Input Offset Current	—	—	—	—	See pad leakage currents in Table 33-10
CM45	IB	Input Bias Current	—	—	—	—	See pad leakage currents in Table 33-10
CM46	IOUT	Output Current	—	—	420	µA	With minimum value of RFEEDBACK (CM48)
CM48	RFEEDBACK	Feedback Resistance Value	8	—	—	kΩ	**(Note 2)**
CM49a	VOUT	Output Voltage	AVSS + 0.075	—	AVDD – 0.075	V	IOUT = 420 µA

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

2: Resistances can vary by ±10% between op amps.

3: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules: ADC, op amp/comparator and comparator voltage reference, will have degraded performance. Refer to Parameter BO10 in Table 33-12 for the minimum and maximum BOR values.

TABLE 33-58: ADCx MODULE SPECIFICATIONS (10-BIT MODE)

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)(1) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
ADC Accuracy (10-Bit Mode)							
AD20b	Nr	Resolution	10 Data Bits			bits	
AD21b	INL	Integral Nonlinearity	-0.625	—	0.625	LSb	-40°C ≤ TA ≤ +85°C **(Note 2)**
			-1.5	—	1.5	LSb	+85°C < TA ≤ +125°C **(Note 2)**
AD22b	DNL	Differential Nonlinearity	-0.25	—	0.25	LSb	-40°C ≤ TA ≤ +85°C **(Note 2)**
			-0.25	—	0.25	LSb	+85°C < TA ≤ +125°C **(Note 2)**
AD23b	GERR	Gain Error	-2.5	—	2.5	LSb	-40°C ≤ TA ≤ +85°C **(Note 2)**
			-2.5	—	2.5	LSb	+85°C < TA ≤ +125°C **(Note 2)**
AD24b	EOFF	Offset Error	-1.25	—	1.25	LSb	-40°C ≤ TA ≤ +85°C **(Note 2)**
			-1.25	—	1.25	LSb	+85°C < TA ≤ +125°C **(Note 2)**
AD25b	—	Monotonicity	—	—	—	—	Guaranteed
Dynamic Performance (10-Bit Mode)							
AD30b	THD	Total Harmonic Distortion(3)	—	64	—	dB	
AD31b	SINAD	Signal to Noise and Distortion(3)	—	57	—	dB	
AD32b	SFDR	Spurious Free Dynamic Range(3)	—	72	—	dB	
AD33b	FNYQ	Input Signal Bandwidth(3)	—	550	—	kHz	
AD34b	ENOB	Effective Number of Bits(3)	—	9.4	—	bits	

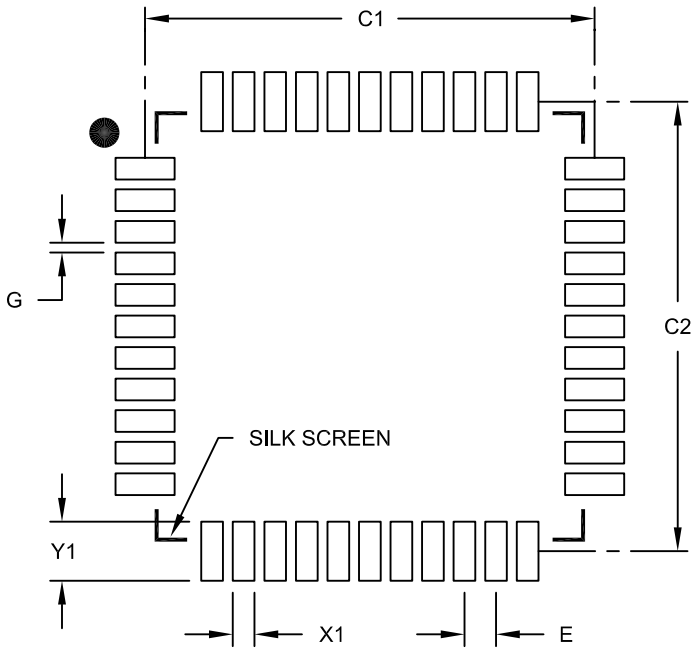
Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules: ADC, op amp/comparator and comparator voltage reference, may have degraded performance. Refer to Parameter BO10 in Table 33-12 for the minimum and maximum BOR values.

2: For all accuracy specifications, VINL = AVSS = VREFL = 0V and AVDD = VREFH = 3.6V.

3: Parameters are characterized but not tested in manufacturing.

44-Lead Plastic Thin Quad Flatpack (PT) 10X10X1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.80 BSC	
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X44)	X1			0.55
Contact Pad Length (X44)	Y1			1.50
Distance Between Pads	G	0.25		

Notes:

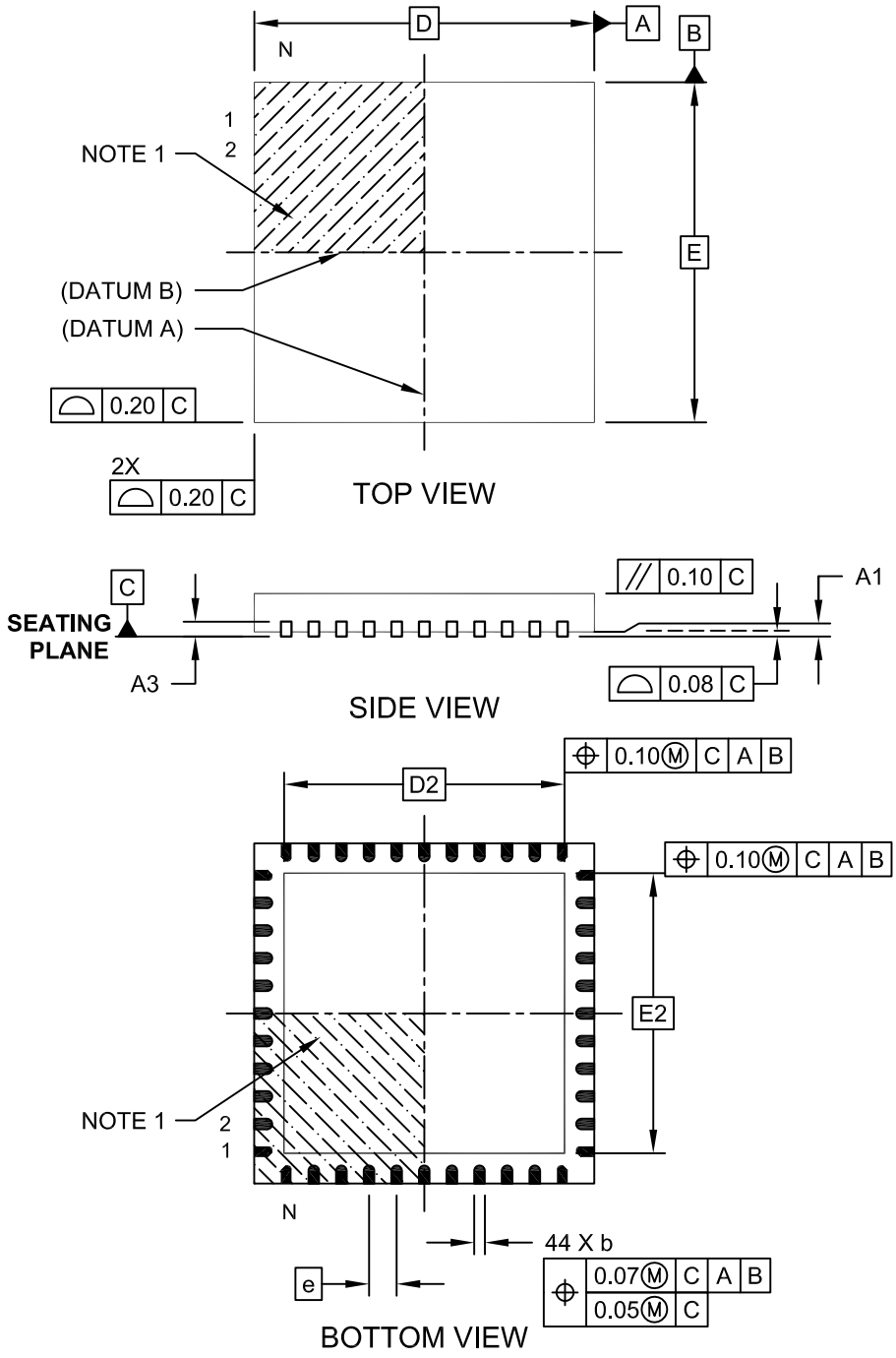
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2076B

44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

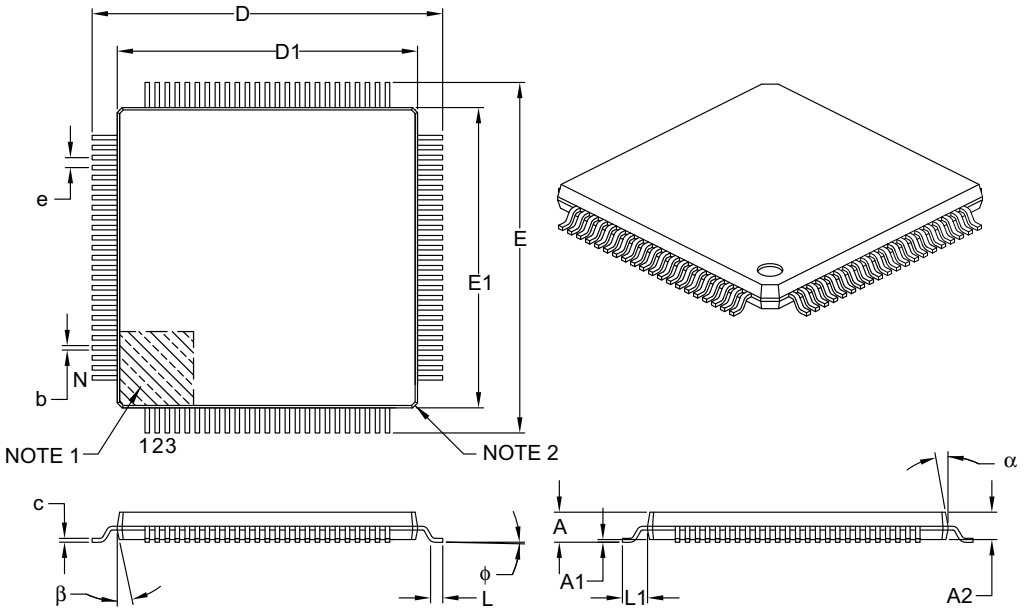
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-103C Sheet 1 of 2

100-Lead Plastic Thin Quad Flatpack (PT) – 12x12x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		100	
Lead Pitch	e		0.40 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		14.00 BSC	
Overall Length	D		14.00 BSC	
Molded Package Width	E1		12.00 BSC	
Molded Package Length	D1		12.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.13	0.18	0.23
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-100B